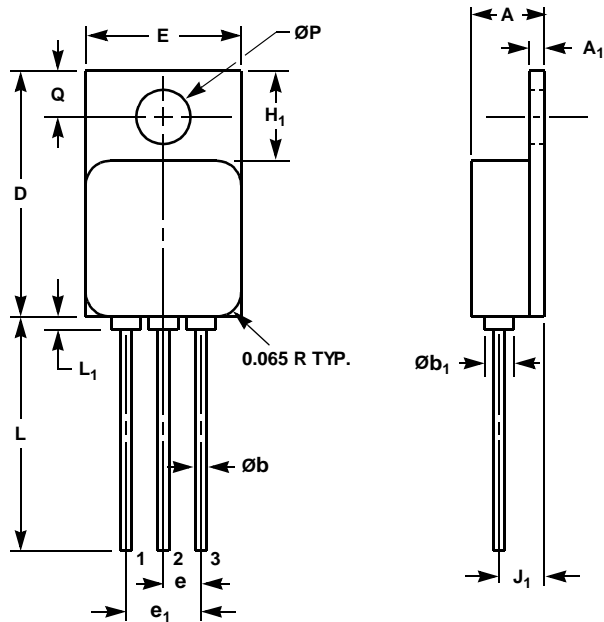


# TO-257AA

## 3 LEAD JEDEC TO-257AA HERMETIC METAL PACKAGE



SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.19	0.200	4.83	5.08	-
A <sub>1</sub>	0.03	0.045	0.89	1.14	-
$\varnothing b$	0.02	0.035	0.64	0.88	2, 3
$\varnothing b_1$	0.06	0.090	1.53	2.28	-
D	0.64	0.665	16.3	16.8	-
E	0.41	0.420	10.4	10.6	-
e	0.100 TYP		2.54 TYP		4
e <sub>1</sub>	0.200 BSC		5.08 BS		4
H <sub>1</sub>	0.23	0.250	5.85	6.35	-
J <sub>1</sub>	0.11	0.130	2.80	3.30	4
L	0.60	0.650	15.2	16.5	-
L <sub>1</sub>	-	0.035	-	0.88	-
$\varnothing P$	0.14	0.150	3.56	3.81	-
Q	0.11	0.133	2.88	3.37	-

### NOTES:

1. These dimensions are within allowable dimensions of Rev. B of JEDEC TO-257AA dated 9-88.
2. Add typically 0.002 inches (0.05mm) for solder coating.
3. Lead dimension (without solder).
4. Position of lead to be measured 0.150 inches (3.81mm) from bottom of dimension D.
5. Die to base BeO isolated, terminals to case ceramic isolated.
6. Controlling dimension: Inch.
7. Revision 1 dated 1-93.